ASEP Solutions

ASEP* Solutions is a next-generation manufacturing technology that integrates multiple functions into a single device to act as the backbone of an electronics system

Features and Benefits

- Continuous-flow manufacturing. Fewer manufacturing process steps. Reduces manufacturing costs. Produces higher yields
- Enables product advantages that might not have been available before. Supports next-generation technological developments
- Hermetically sealed package. Prevents water and dust ingress. Withstands harsh environment
- Applicable for a wide range of markets. Provides a versatile solution with wide-ranging applications
- Thermal management features integrated into device. Enables heat dissipation without exacerbating space constraints
- Integrates electronic functions directly into end product. Reduces or eliminates more common packaging and PCBs. Frees up valuable real estate. Enables devices to shrink and weigh less, making end products more convenient and comfortable
- Enables cameras and sensors to be integrated directly into product. Promotes compactness. Reduces device weight. Automated process makes it cost effective

*Application Specific Electronics Packaging
ASEP Solutions

Applications

Consumer
- AR/VR headsets
- Smart glasses
- Mobile devices
- Sensors

Home Appliance
- Power supplies
- Sensors
- Cameras

Medical
- Small devices with packaging design challenges
- High-volume disposables
- Smart glasses

Automotive
- Lighting modules
- In-vehicle electronics
- Cameras
- DC-to-DC converters
- Power control modules
- Sensors

Industrial
- Smart glasses
- Sensors

Note: Molex reserves the right to delay or cancel production of the depicted product without additional notice. Please contact your Molex customer service representative for product availability.

www.molex.com/link/asep.html